

Crydom

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TP01 / TP03 / TP01-C Thermal Transfer Pads

	Material	Thermal Impedance °C/W (Area:T0.3)	Volume Resistivity Wcm	Temperature Range
Property	Compressed Graphite	0.07	0.002	-200 to +500 °C
Test Method		ASTM D5470	ASTM D991 (Mod)	

	Description
	TP Series is a dry alternative to thermal compound. Its composition is 98% graphite and by nature offers both thermal and electrical conductivity. Low thermal resistance means that TP Series can be used in high power applications where maximum heat transfer is essential. High electrical conductivity is a natural property because of the graphite structure. TP Series provides a consistent low resistance path between Solid State Relays and Heatsink. Contamination is eliminated because TP Series does not outgas or migrate like thermal compounds. It does not shrink or dry out.

Ordering Information	Key Performance Properties
An extensive range of pre-cut profiles to suit a range of Crydom Solid State Relays. TP01 - S1 Series TP03 - 53TP Series TP01-C - CMD Series	Extremely low thermal resistance.
	Fills air gaps between components up to 7 % of the pads thickness.
	Remains resistant to cleaning agents, and does not support organic growth.
	No known deterioration over time.
	Easily installed reducing assembly time to minimum.

Technical Information	Property	Test Standard
Thickness (mm)	0.200 ± 0.02	
Thermal Conductivity Wm ⁻¹ K ⁻¹	3.85	MIL-I-49456A
Thermal resistance per cm ²	0.45°C/W	
Hardness	84 ± 5	Shore Micro
Tear Resistance kN/m	8	ASTM D624
Tensile Strength MPa	3.6	ASTM D412
Dielectric Constant 1000Hz	N/A	ASTM D150
Elongation %	1	ASTM D412
Colour	Dark grey	

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